

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A method of polishing and then cleaning substrates, comprising:
polishing a first substrate by pressing said first substrate against a first polishing surface; then
primarily cleaning said first substrate in a first of two first cleaning units; then
secondarily cleaning said first substrate in a common second cleaning unit while supporting said first substrate on a table;
polishing a second substrate by pressing said second substrate against a second polishing surface; then
primarily cleaning said second substrate in a second of said two first cleaning units; and then
secondarily cleaning said second substrate in said common second cleaning unit while supporting said second substrate on said table.

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Claims 2-9 (Cancelled)

10. (Previously presented) The method according to claim 1, wherein
primarily cleaning said first substrate in said first of said two first cleaning units
comprises cleaning said first substrate in said first of said two first cleaning units by subjecting
said first substrate to a first cleaning function, and
primarily cleaning said second substrate in said second of said two first cleaning units
comprises cleaning said second substrate in said second of said two first cleaning units by
subjecting said second substrate to a second cleaning function that is the same as said first
cleaning function.